

CEP35P10

-100V ▲ 63mΩ ▲ -32A ▲ Si MOSFET

SILICON Si MOSFET ▲ THT type

P-channel enhancement mode

UL94V-0 rated flame retardant epoxy

TO220-3L package

Super high dense cell density for extremely low $R_{DS(ON)}$

High power and current handling capability






MAXIMUM RATINGS

Parameter ($T_C = 25^\circ\text{C}$, unless otherwise noted)		Characteristics
Drain-Source Voltage	V_{DS}	-100V
Gate-Source Voltage	V_{GS}	$\pm 20\text{V}$
Continuous Drain Current at $T_C = 25^\circ\text{C}$	I_D	-32A
Pulsed Drain Current ^{Note 1}	I_{DM}	-128A
Maximum Power Dissipation at $T_C = 25^\circ\text{C}$	P_D	125W
Power Dissipation Derating above 25°C	ΔP_D	$0.83\text{W}/^\circ\text{C}$
Single Pulsed Avalanche Energy ^{Note 4}	E_{AS}	450mJ
Single Pulsed Avalanche Current ^{Note 4}	I_{AS}	30A
Operating and Storage Temperature Range	T_J, T_{STG}	-55°C to $+175^\circ\text{C}$

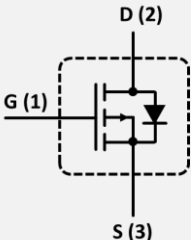
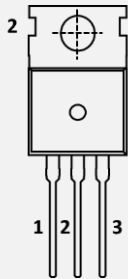
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case	R_{TH_JC}	$1.2^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	R_{TH_JA}	$62.5^\circ\text{C}/\text{W}$

APPLICATIONS

DC/DC Converter	DC Fan	Load Switches	Power Banks	USB Storage
				

PIN DESCRIPTION

Circuit Diagram	Outline - Front View	Pin No.	Description
		1 2 3	Gate Drain Source

ELECTRICAL CHARACTERISTICS ▲ $T_C = 25^\circ\text{C}$, unless otherwise noted

Item	Condition	Symbol	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	BV_{DSS}	-100			V
Zero Gate Voltage Drain Current	$V_{DS} = -100V, V_{GS} = 0V$	I_{DSS}			-1	μA
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I_{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	I_{GSSR}			-100	nA
On Characteristics ^{Note 2}						
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu A$	$V_{GS(th)}$	-1		-3	V
Static Drain-Source On-Resistance	$V_{GS} = -10V, I_D = -16A$	$R_{DS(ON)}$		63	76	m Ω
Static Drain-Source On-Resistance	$V_{GS} = -4.5V, I_D = -8A$	$R_{DS(ON)}$		72	92	m Ω
Dynamic Characteristics ^{Note 3}						
Input Capacitance	$V_{DS} = -25V, V_{GS} = 0V, f = 1MHz$	C_{ISS}		2590		pF
Output Capacitance	$V_{DS} = -25V, V_{GS} = 0V, f = 1MHz$	C_{OSS}		320		pF
Reverse Transfer Capacitance	$V_{DS} = -25V, V_{GS} = 0V, f = 1MHz$	C_{RSS}		45		pF
Switching Characteristics ^{Note 3}						
Turn-On Delay Time	$V_{DD} = -50V, V_{GS} = -10V, I_D = -18A, R_{G(ext)} = 3.3\Omega$	$t_{D(ON)}$		17		ns
Turn-On Rise Time	$V_{DD} = -50V, V_{GS} = -10V, I_D = -18A, R_{G(ext)} = 3.3\Omega$	t_R		6		ns
Turn-Off Delay Time	$V_{DD} = -50V, V_{GS} = -10V, I_D = -18A, R_{G(ext)} = 3.3\Omega$	$t_{D(OFF)}$		75		ns
Turn-Off Fall Time	$V_{DD} = -50V, V_{GS} = -10V, I_D = -18A, R_{G(ext)} = 3.3\Omega$	t_F		10		ns
Total Gate Charge	$V_{DS} = -80V, V_{GS} = -10V, I_D = -18A$	Q_G		75		nC
Gate Source Charge	$V_{DS} = -80V, V_{GS} = -10V, I_D = -18A$	Q_{GS}		9		nC
Gate Drain Charge	$V_{DS} = -80V, V_{GS} = -10V, I_D = -18A$	Q_{GD}		18		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current		I_S			-32	A
Drain-Source Diode Forward Voltage ^{Note 2}	$V_{GS} = 0V, I_S = -16A$	V_{SD}			-1.2	V

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
- 3: Guaranteed by design, not subject to production testing.
- 4: $L = 1mH, I_{AS} = 30A, V_{DD} = 25V, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$

REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 1 • Output Characteristics

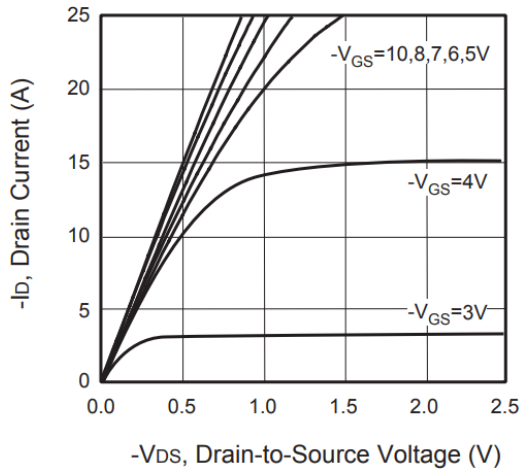


Fig. 2 • Transfer Characteristics

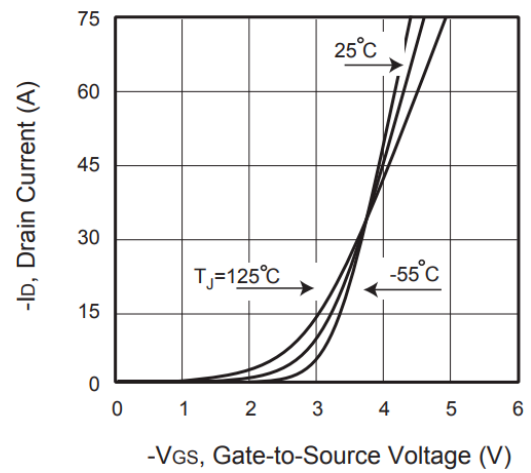


Fig. 3 • Capacitance

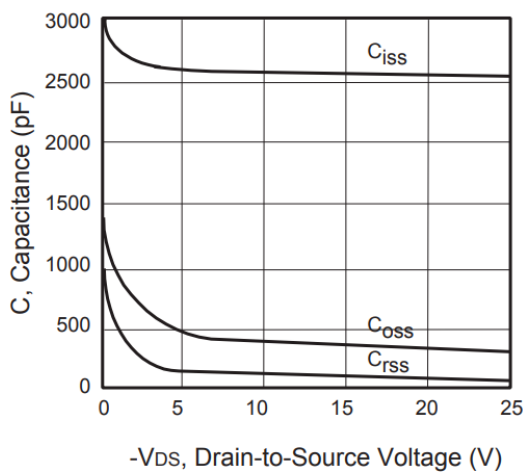


Fig. 4 • On-Resistance Variation with Temperature

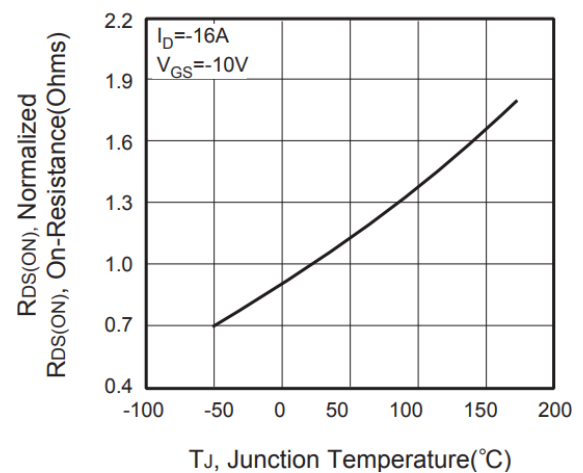


Fig. 5 • Gate Threshold Variation with Temperature

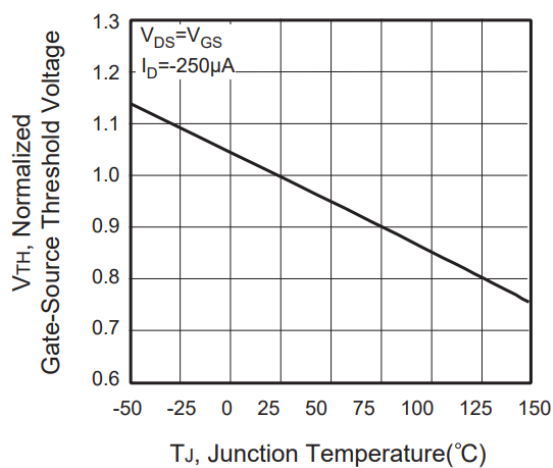
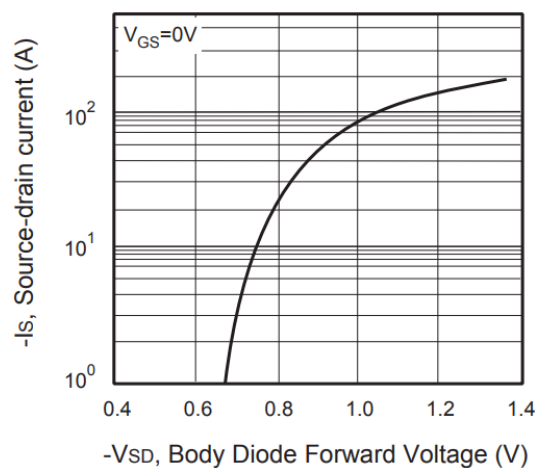


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 7 • Gate Charge

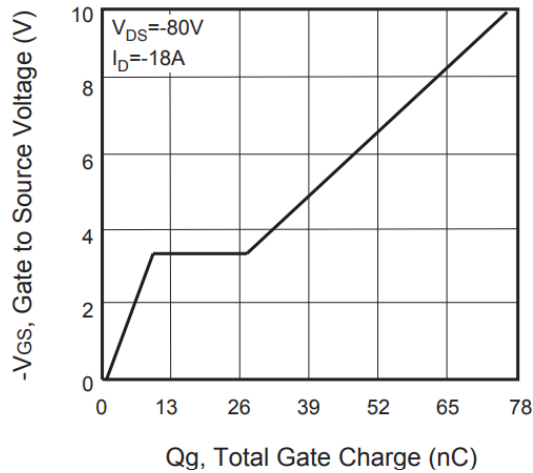


Fig. 8 • Maximum Safe Operating Area

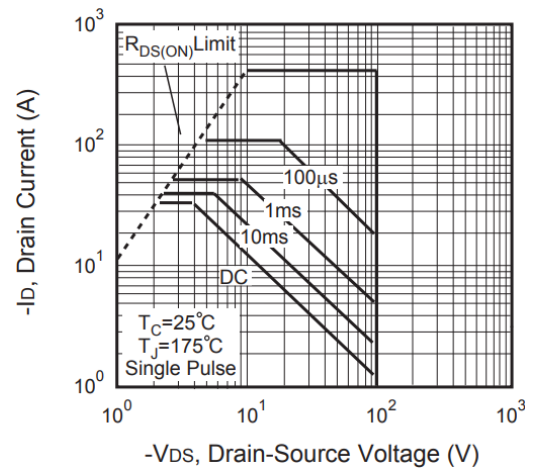


Fig. 9 • Switching Test Circuit

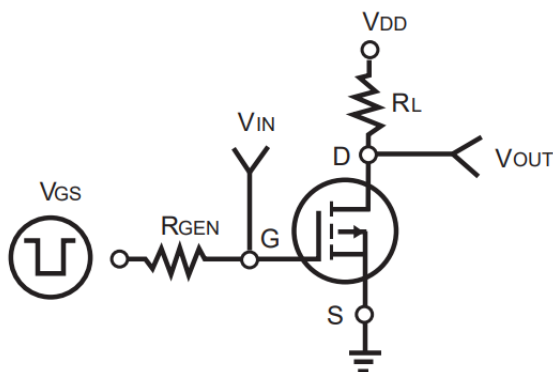


Fig. 10 • Switching Waveforms

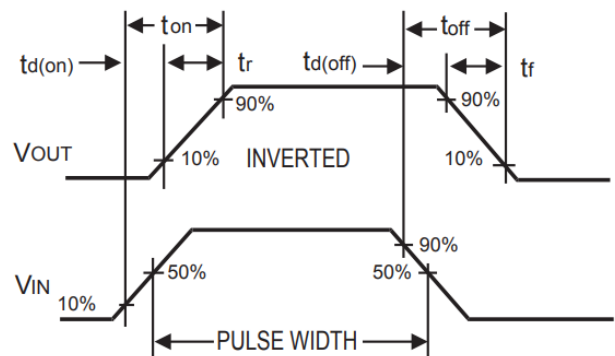
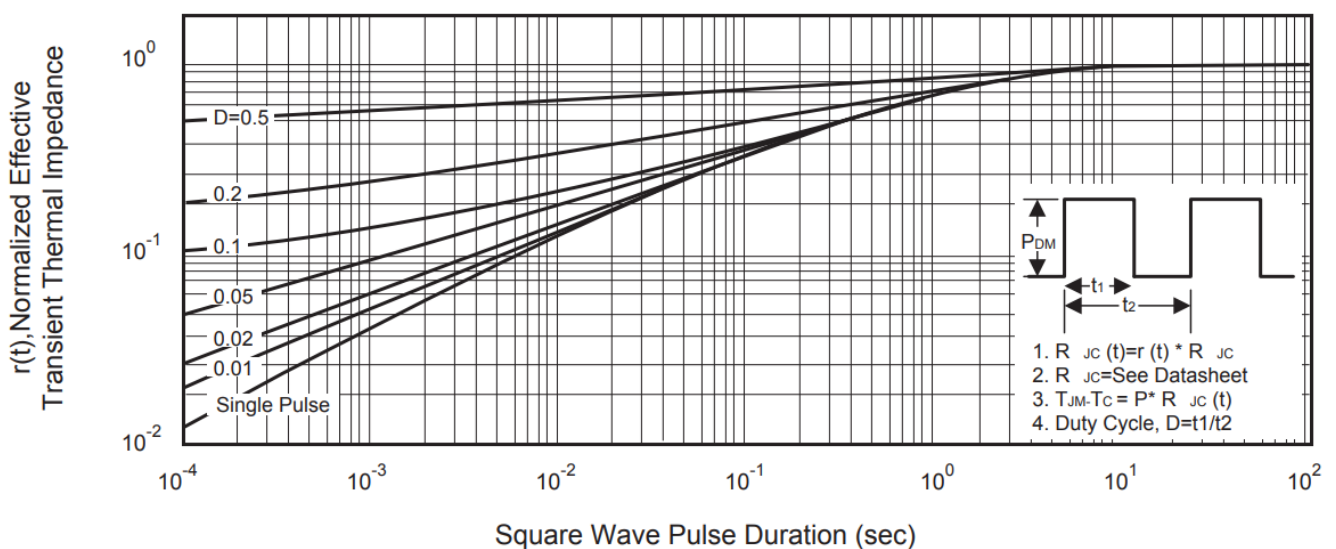
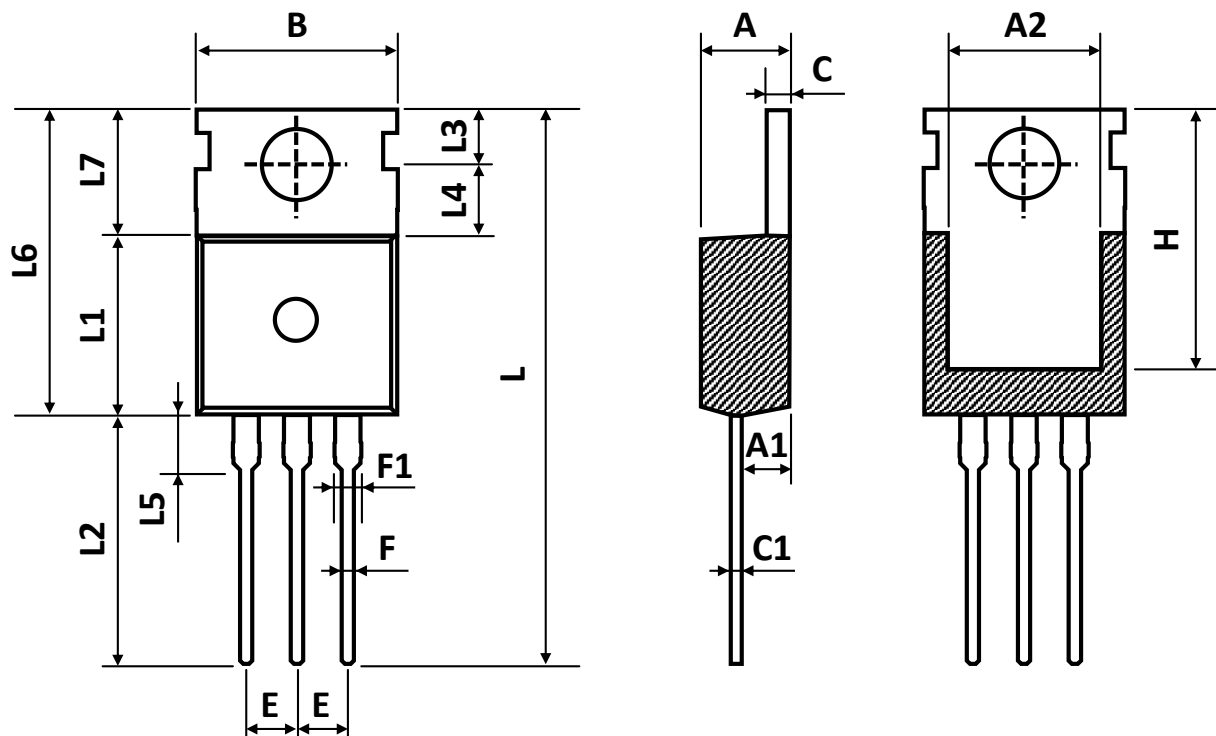


Fig. 11 • Normalized Thermal Transient Impedance Curve



PACKAGE OUTLINE

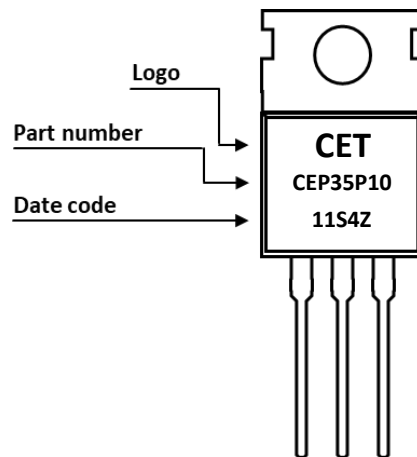


Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
A	4.43	4.53	4.63
A1	2.30	2.40	2.50
A2	7.70	7.90	8.10
B	9.80	10.00	10.20
C	1.25	1.30	1.40
C1	0.45	0.50	0.60
D	3.45	3.60	3.70
E	2.45	2.54	2.60
F	0.70	0.80	0.95
F1	1.15	1.33	1.50
L	26.80	28.80	30.80
L1	9.20	9.30	9.40
L2	12.80	13.10	13.40
L3	2.70	2.80	2.90
L4	3.50	3.70	3.80
L5	2.60	2.90	3.20
L6	15.40	15.80	16.20
L7	6.20	6.50	6.80
H	12.95	13.25	13.55

ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
CEP35P10	TO-220-3L	Tube	50pcs	1,000pcs	4,000pcs

PART MARKING



DATE CODE

Example: 11S4Z



Coding list for „Day“

1	2	3	4	5	6	7	8	9	A
01	02	03	04	05	06	07	08	09	10
B	C	D	E	F	G	H	I	J	K
11	12	13	14	15	16	17	18	19	20
L	M	N	O	P	Q	R	S	T	U
21	22	23	24	25	26	27	28	29	30
V									
31									

Coding list for „Month“

1	2	3	4	5	6
Jan	Feb	Mar	Apr	May	Jun
7	8	9	A	B	C
Jul	Aug	Sep	Oct	Nov	Dec

Coding list for „Year“

0	1	2	3	4
2020	2021	2022	2023	2024
5	6	7	8	9
2025	2026	2027	2028	2029

RECOMMENDED WAVE SOLDERING PROFILE ▲ THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	$T_{s\ min}$	100 °C	100 °C
Preheat temperature typical	$T_{s\ typ}$	120 °C	120 °C
Preheat temperature max.	$T_{s\ max}$	130 °C	130 °C
Preheat time t_s from $T_{s\ min}$ to $T_{s\ max}$	t_s	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t_p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down rate min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second
Time 25°C to 25°C		4 minutes	4 minutes

REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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